

APPARATUS, TRANSFER METHOD, CHAMBER AND FRAME FOR SEMICONDUCTOR BURN-IN PROCESS

Abstract

The present disclosure relates to burn-in apparatus, transfer method, burn-in chamber, and interchangeable frame thereof for semiconductor devices burn-in process. The burn-in apparatus comprises of a burn-in chamber with an incomplete base which is adapted to be completed and thermally insulated in cooperation with a thermal insulation base of at least one interchangeable frame which is adapted to be removably moved into and docked in the burn-in chamber to complete the burn-in apparatus. The burn-in apparatus comprises the burn-in chamber and at least one frame. The apparatus is complete and thermally insulated when the frame is moved into the burn-in chamber and docked therein. The apparatus is incomplete and thermally uninsulated when the frame is moved out of the burn-in chamber and undocked therefrom.

Figure 1